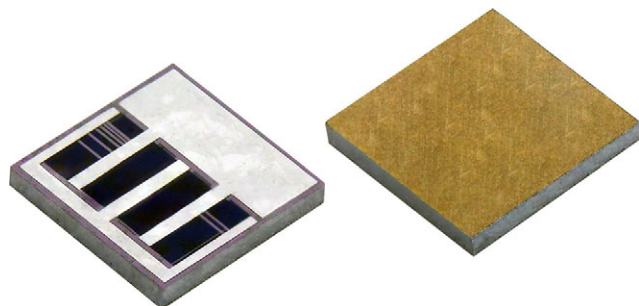


## Thin Film, High Power Back-Contact Resistor



### LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

[Videos](#)

[Infographics](#)

[Did You Know?](#)

[Capabilities and Custom Options](#)

The IGBR series is an AEC-Q200 qualified thin film resistor that utilizes the excellent thermal properties of silicon to allow ultra high power rating in a miniature case size for sinterable and hybrid assemblies.

The IGBR's back contact design requires only one wire bond thus saving hybrid space.

The IGBR's are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology.

The IGBR's are 100 % electrically tested and visually inspected to automotive, military, or commercial inspection per internal standards.

### FEATURES

- AEC-Q200 qualified available, produced in ITAF 16949 certified facility
- Designed to operate at elevated temperatures up to 200 °C
- Noise reduction or elimination when used in SiC power modules
- Sintering, soldering, and epoxy attachment options
- Single wire bond assembly
- Moisture resistant
- Case size: 0202 to 0808
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
**GREEN**  
(5-2008)

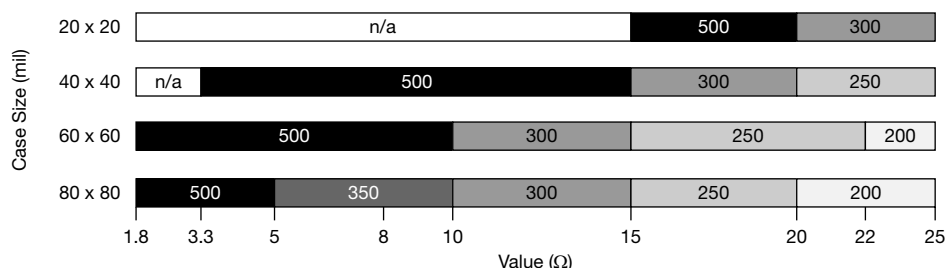
### APPLICATIONS

- Current balancing resistor for SiC, GaN, and IGBT power modules
  - Automotive electrification
  - High power MRI
  - Industrial HVAC
  - Alternative energy
- LED lighting
- Hybrid assemblies
- Data management servers

### TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES

PARAMETER	VALUE	UNIT
Total Resistance Range	1.8 to 25	Ω
Standard Tolerances	5, 10, 25	%
TCR	± 500	ppm/°C

### TCR (ppm/°C) BY CASE SIZE AND VALUE



**STANDARD ELECTRICAL SPECIFICATIONS**

PARAMETER	VALUE	UNIT
Operating Film Temperature Range	250 max.	°C
Operating Temperature Range	-55 to +200	°C
Working Voltage	75 max.	V
Breakdown Voltage	400 max.	V
DC Power Rating <sup>(1)</sup>	Up to 4	W
Load Life Stability, 1000 h, Film Temperature 200 °C	$\pm 1 \Delta R/R$	%
Short Time Overload, 2.5 x Rated Power, 25 °C, 5 s	$\pm 0.25 \Delta R/R$	%
Thermal Shock, MIL-STD-202, Method 107 F	$\pm 1 \Delta R/R$	%
Moisture Resistance, MIL-STD-202, Method 106	$\pm 0.25 \Delta R/R$	%
High Temperature Exposure, 100 h, +200 °C	$\pm 0.5 \Delta R/R$	%
Low Temperature Operation, -65 °C, 45 min	$\pm 0.5 \Delta R/R$	%

**Notes**

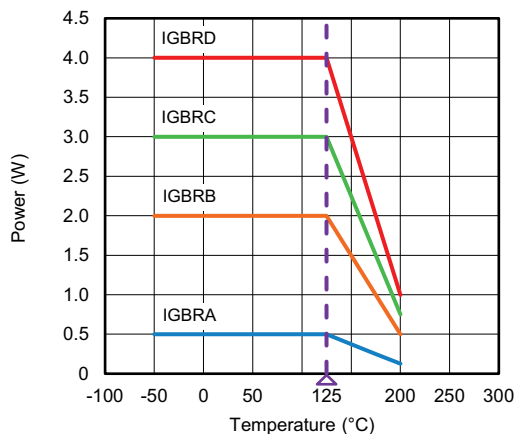
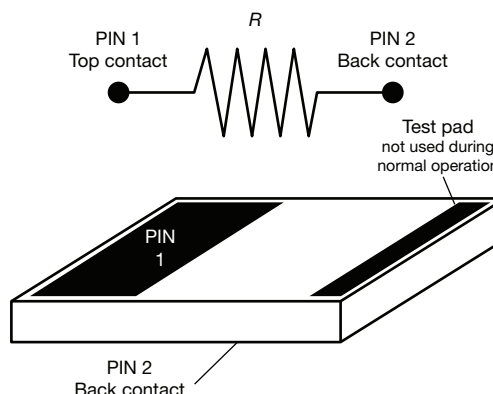
- <sup>(1)</sup> Power rating determined by application specific heat sink properties. See table "Power Rating by Case Size" for more details
- AEC-Q200 testing specifications available upon request

**POWER RATING BY CASE SIZE**

CASE SIZE	CHIP SIZE mil (mm) <sup>(1)</sup>	BOND PAD SIZE mil (mm)	DIE THICKNESS mil (mm) <sup>(2)</sup>	MAX. POWER (W) <sup>(1)</sup>	R MIN. Ω	R MAX. Ω
0202	20 x 20 (0.51 x 0.51)	10 x 16 (0.25 x 0.41)	10 (0.25)	0.5	15	25
0404	40 x 40 (1.02 x 1.02)	15 x 36 (0.38 x 0.91)	10 (0.25)	2	3.3	25
0606	60 x 60 (1.52 x 1.52)	20 x 56 (0.51 x 1.42)	10 (0.25)	3	1.8	25
0808	80 x 80 (2.03 x 2.03)	27 x 76 (0.69 x 1.93)	10 (0.25)	4	1.8	25

**Notes**




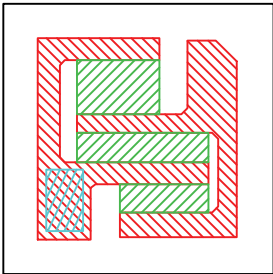
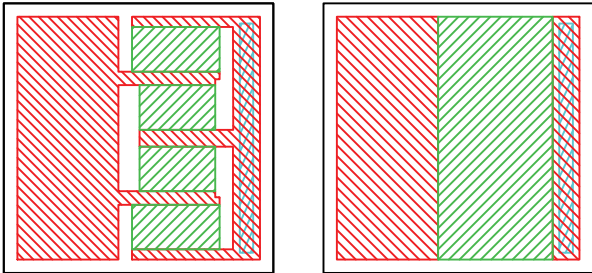
- <sup>(1)</sup> Dimension tolerances are  $\pm 0.051$  mm ( $\pm 2$  mil)
- <sup>(2)</sup> Typical maximum power between film and back contact. Does not include die attach joint (epoxy or solder)

**POWER DERATING CURVES**

**SCHEMATIC**


MATERIAL SPECIFICATIONS	
PARAMETER	
MSL Designation	MSL1 (floor life unlimited)
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO <sub>2</sub>
Film Material	Tantalum Nitride
Case Size	See table "Power Rating by Case Size"
Passivation	None
Number of Pads	1
Top Terminations Suitable for Aluminum Wire-Bonding	Al (2.5 µm min.)
Back Termination (for epoxy, lead (Pb)-free solder, or sintering assembly)	S = Ti (800 Å to 1200 Å) NiV (1600 Å to 2400 Å) Ag (5000 Å to 7000 Å)
	P = TiW (500 Å to 1000 Å) Pd (2000 Å to 3000 Å) Au (3000 Å to 5000 Å)
	N = TiW (500 Å to 1000 Å) Ni (6000 Å to 7000 Å) Au (3000 Å to 5000 Å)
	T = TiW (500 Å to 1000 Å) Au (1000 Å to 3000 Å) Ni (40 µ" minimum) Au (40 µ" minimum)

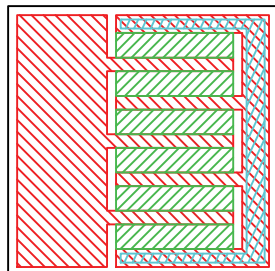
**Note**

- This product was qualified using 1 mil Al wire at 3 g min pull force

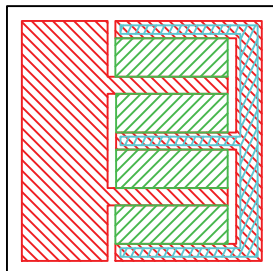
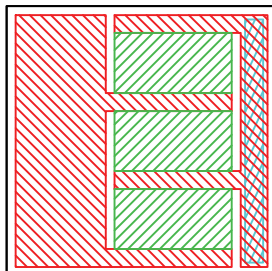
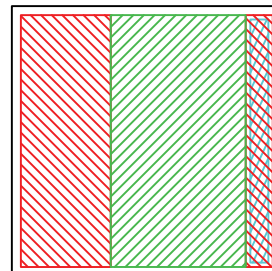
MATERIAL SPECIFICATIONS	
 Conductor material	 Resistor material  Backside connection
<b>VERSION A (0202)</b>	
	
IGBRA - 15 Ω to 25 Ω	
<b>VERSION B (0404)</b>	
	
IGBRB - 3.3 Ω to 12.9 Ω <sup>(1)</sup> IGBRB - 13 Ω to 25 Ω	

**MATERIAL SPECIFICATIONS**

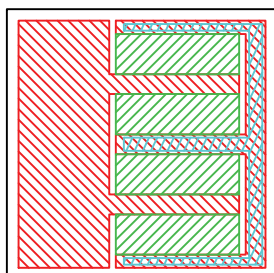
Conductor material    
 Resistor material    
 Backside connection

**VERSION C (0606)**


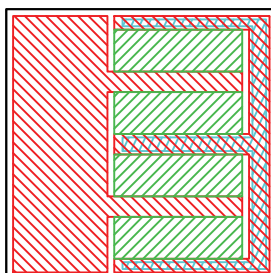
IGBRC - 1.8 Ω to 2.9 Ω


 IGBRC - 3 Ω to 5.5 Ω <sup>(1)</sup>

 IGBRC - 5.6 Ω to 15.90 Ω <sup>(1)</sup>


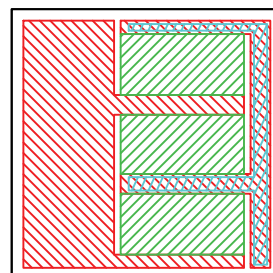
IGBRC - 16 Ω to 25 Ω

**VERSION D (0808)**


IGBRD - 1.8 Ω to 5.5 Ω



IGBRD - 5.6 Ω to 14.9 Ω



IGBRD - 15 Ω to 24.9 Ω

**Note**
<sup>(1)</sup> AEC-Q200 qualified available

**GLOBAL PART NUMBER INFORMATION**

Global Part Number: IGBRB3000CJOPCST

Global Part Number Description: IGBR 1 mm 3 Ω 5 % 300 ppm/°C PD Commercial Tape

I	G	B	R	B	3	0	0	0	C	J	O	P	C	S	T
MODEL	SIZE	RESISTANCE (Ω)	RESISTANCE MULTIPLIER CODE	TOL. CODE (%)	TCR (ppm/°C)	BACKSIDE TERMINATION	QUALIFICATION LEVEL	PACKAGING CODE							
<b>IGBR</b>  High power back- contact resistor	<b>A</b> = 20 x 20 <b>B</b> = 40 x 40 <b>C</b> = 60 x 60 <b>D</b> = 80 x 80	First 4 digits are significant figures of resistance	<b>C</b> = 0.001 <b>B</b> = 0.01 <b>A</b> = 0.1	<b>J</b> = 5 <b>K</b> = 10 <b>M</b> = 20 <b>L</b> = 25	<b>J</b> = ± 500 <b>W</b> = ± 350 <b>O</b> = ± 300 <b>M</b> = ± 250	<b>S</b> = Ti / NiV / Ag <b>P</b> = TiW / Pd / Au <b>N</b> = TiW / Ni / Au <b>T</b> = TiW / Au / Ni/Au <sup>(1)</sup>	<b>A</b> = automotive <sup>(2)</sup> <b>M</b> = military <sup>(3)</sup> <b>C</b> = commercial version 1 <sup>(4)</sup> <b>C2</b> = commercial version 2 <sup>(4)</sup>	<b>WS</b> = waffle pack 100 min., 1 mult. <b>ST</b> = diced on tape <b>TF</b> = tape and reel 5000 min., 1 mult.							

**Notes**

- <sup>(1)</sup> See "Material Specifications" table for metal thickness
- <sup>(2)</sup> AEC-Q200 qualified, IATF 16949 certified
- <sup>(3)</sup> Visually inspected to MIL-STD-883 M2032 Class H
- <sup>(4)</sup> Vishay internal control standards



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